**SPECIFICATIONS**

**CURRENT RATING**
1 AMP

**INSULATOR RESISTANCE**
1000 MEGOHMS MIN.

**CONTACTS RESISTANCE**
20m OHMS MAX.

**DIELECTRIC WITHSTANDING**
AC 300 V

**OPERATING TEMPERATURE**
-40°C TO +105°C

**CONTACT MATERIAL**
PHOSPHOR BRONZE

**INSULATOR MATERIAL**
THERMOPLASTIC, UL 94V-0

**PLATING**
GOLD, TIN, OR SELECTIVE OVER 30-50% NICKEL

**SOLDERABILITY**
IR REFLOW: 280°C FOR 10 SEC
WAVE: 250°C FOR 5-10 SEC
MANUAL SOLDER: 380°C FOR 3-5 SEC

**NOTES:**
1. **RECOMMENDED MATING PIN LENGTH:** 3.0MM

**MATES WITH:**
- BB02-BG
- BB02-BS
- BB02-BD
- BB02-BY
- BB02-BE
- BB02-BZ
- BB02-BK
- BB02-NE
- BB02-BP

**RECOMMENDED PCB BOARD HOLED LAYOUT**
(TOLERANCE: ±0.05)

**HOW TO ORDER**

- **BB02-XXXX**
- **C0XX2**
- **X0X**
- **X0000000**

**CONTACT PLATING OPTIONS**
- K = GOLD FLASH (STANDARD)
- A = 10u GOLD ON CONTACT/GOLD FLASH ON TAIL
- B = 15u GOLD ON CONTACT/GOLD FLASH ON TAIL
- C = 30u GOLD ON CONTACT/GOLD FLASH ON TAIL
- T = BRIGHT TIN
- M = MATT TIN
- D = GOLD FLASH ON CONTACT/BRIGHT TIN ON TAIL

**PACKING OPTIONS**
- 3 = TUBE
- 4 = TUBE & FILM
- 5 = TUBE & CAP
- 6 = T-R
- 7 = T-R + FILM
- 8 = T-R + CAP

**WITH OR WITHOUT LOCATING FEG**
- A = WITH FEG
- B = WITHOUT FEG

**SCALE**
5:1

**THIRD ANGLE**

**TYPE**
BB02-CU

**DRAWN BY**

**DATE**
5 OCT 12

**REVISION**
1.0

**UNIT**
mm

**COMPANY**
GradConn

**WEBSITE**
www.gradconn.com

**COPYRIGHT**
(C) THIS DRAWING CONTAINS CONFIDENTIAL INFORMATION OF GRADCONN. CANDTBE REPRODUCED WITHOUT WRITTEN PERMISSION.